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**(54) Title (EN):** PROTECTIVE FILM FORMING COMPOSITE SHEET AND METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP

**(54) Title (FR):** FEUILLE COMPOSITE DE FORMATION DE FILM DE PROTECTION ET PROCÉDÉ DE FABRICATION D'UNE PUCE SEMI-CONDUCTRICE

**(54) Title (JA):** 保護膜形成用複合シート、及び半導体チップの製造方法

**(57) Abstract:**

**(EN):** According to the present invention, the half-life of the charged voltage of a protective film forming composite sheet (101) is set to 20 seconds or less, the protective film forming composite sheet being provided with: a support sheet (10); and a protective film forming film (13) formed on a first surface (10a) of the support sheet (10).

**(FR):** Selon la présente invention, la demi-vie de la tension chargée d'une feuille composite de formation de film de protection (101) est fixée à 20 secondes au maximum, la feuille composite de formation de film de protection étant pourvue : d'une feuille de support (10) ; et d'un film de formation de film de protection (13) formé sur une première surface (10a) de la feuille de support (10).

**(JA):** 支持シート(10)と、支持シート(10)の第1面(10a)上に形成された保護膜形成用フィルム(13)と、を備えた保護膜形成用複合シート(101)の帯電圧の半減期を、20秒以下とする。

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